

Overview of the Back-End Design of Digital Chips

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1. Overview of the Back-end

2. Logical synthesis

3. Timing analysis

4. Place & Route

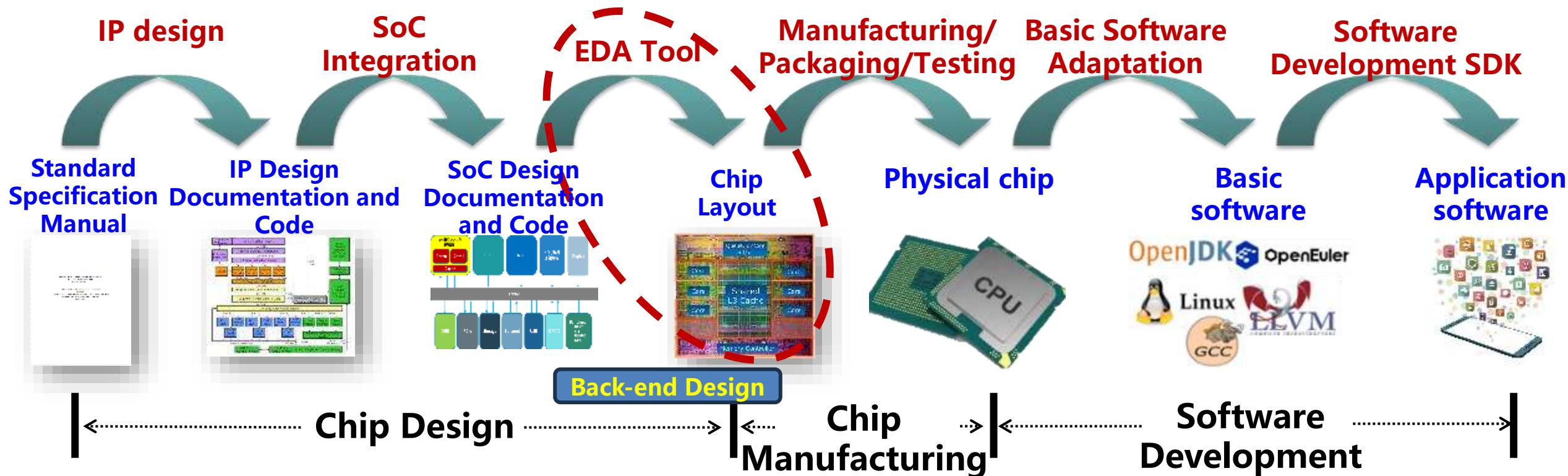
5. Physical verification

1. Overview of the Back-end

■ **Digital chip design** : Translating functional requirements into manufacturable silicon chip circuits

■ Front-end design: Design and verification of RTL

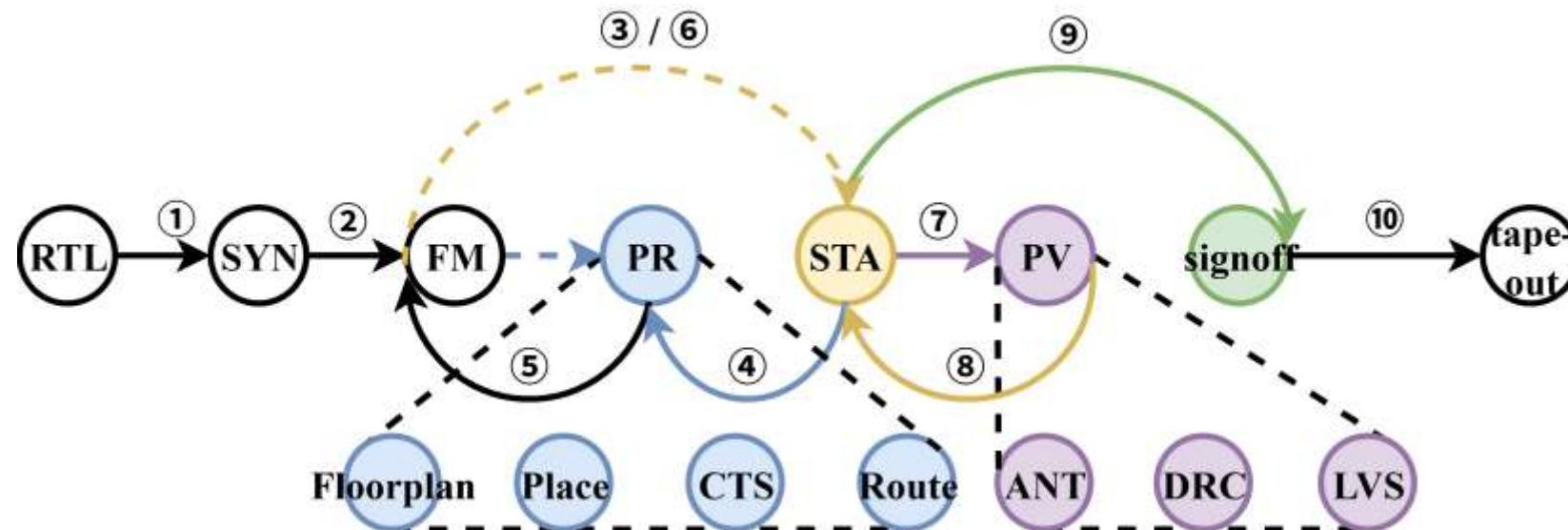
■ **Back-end design: From RTL (Netlist) to the generation of GDS**



1. Overview of the Backend

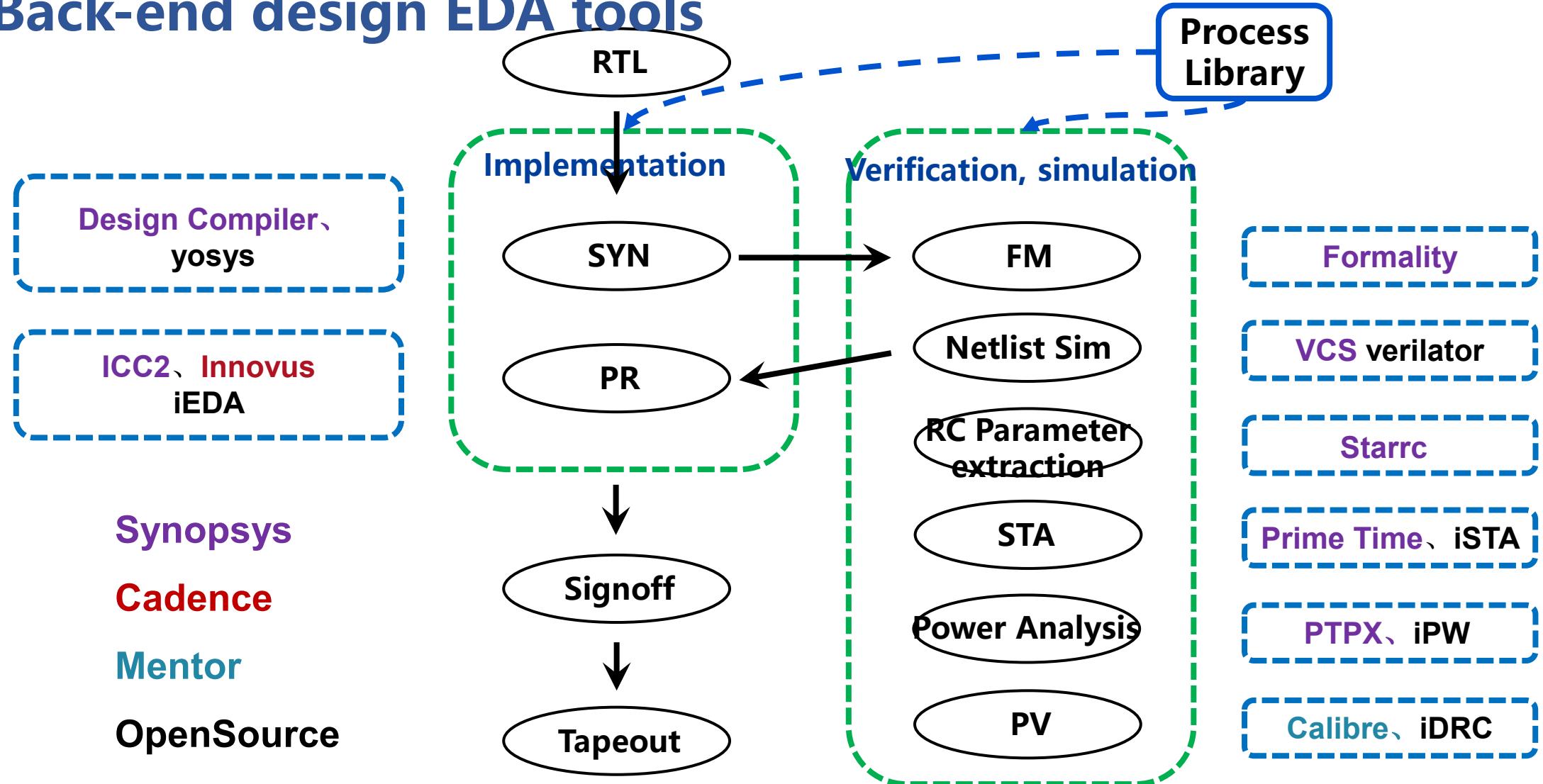
■ Back-end design process

- Logical synthesis (SYN)
- Formal verification (FM)
- Static timing analysis (STA)
- Place & Route (PR)
- Physical verification (PV)
- Signoff
- Floorplan
- ERC
- Place
- DRC
- CTS
- LVS
- Route
- Tape out



1. Overview of the Backend

■ Back-end design EDA tools



1. Overview of the Backend

■ ECOS (EDA、Chip、One-Student-One-Chip、System)

SoC Template
Select SoC template from the IP Market

Float Panel System
Support the dragging, resizing operations and customized data

Advanced extensible Layout Editor

Cloud-based Agile EDA Platform
iEDA Inside
“An open-source EDA infrastructure”
(support ICS55/SKY130/IHP130)

ECOS Studio
“Componentization of Data”

Dashboard

Merge to Latest Shuttle

Real-time Collaboration*
Flow →
Architecture
RTL/Verify
Backend
Pipeline Mode
*: this feature will be released in 2025Q4

1. Overview of the Backend

- Supports one-stop RISC-V processor SoC chip design and tape-out using open-source EDA tools, open-source IP, and open-source PDK

Submit Design
(Processor core/IP/...)

```
1 module ysyx_23060171_idu(
2     input [6:0]opcode,
3     input [2:0]f3,
4     input [6:0]f7,
5     output [2:0]alucontrol,
6     output Regwrite,
7     output [2:0]immtype
8 );
9     assign alucontrol = 3'b000;
10    assign Regwrite = 1;
11    assign immtype = 3'b000;
12 endmodule
```

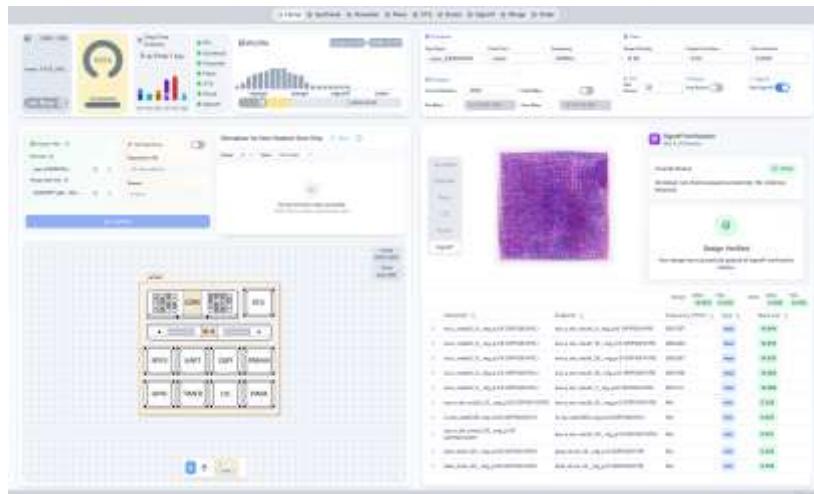


Home delivery
(Chip + Board)

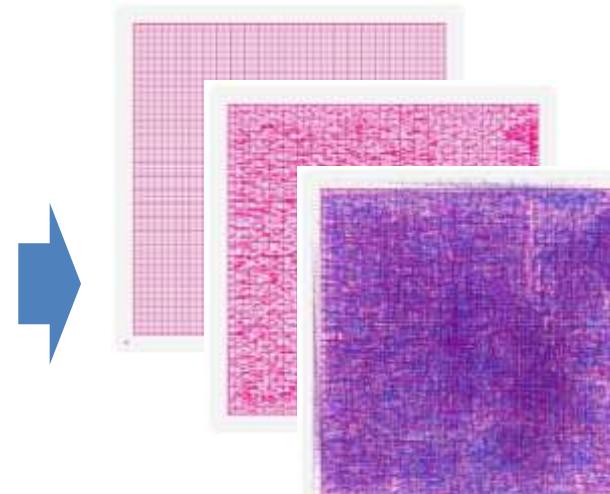


1. Overview of the Backend

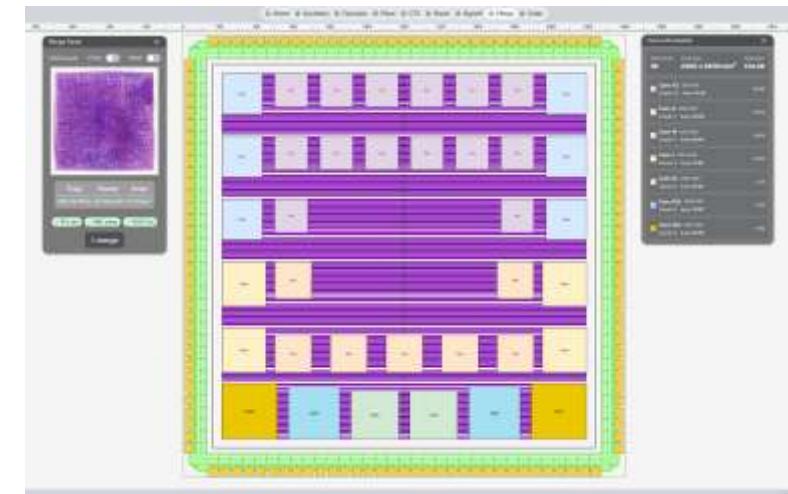
■ Supports end-to-end layout design of 100,000 instances of chips from RTL to GDSII on ICsprout 55nm process



Home interface



Layout render effect



Merge interface

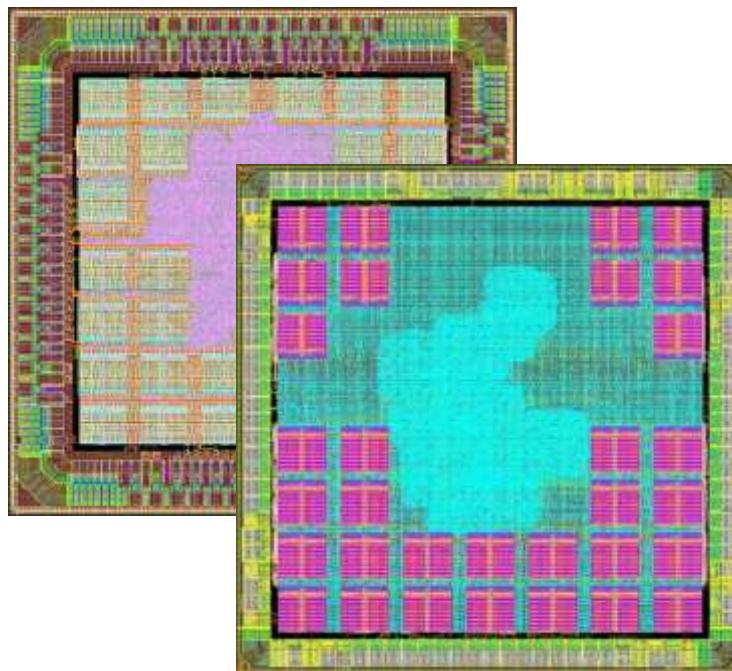


1. Overview of the Backend

■ Two chips designed based on ICsprout 55nm process have been fabricated and are running successfully



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A screenshot of a terminal window displaying boot logs for the ECOS chip. The logs include initialization messages, memory map, and other diagnostic information.

Design: A RV32IMAC SoC(PSRAM, QSPI, UART, I2C, PWM, TIMER, RNG).
Size: 4mm²(128KB OCM, no PLL)

Freq: 100MHz(external clock bypass)
Gates: 1.517M(73,009 cells) Power: 115.4mW(dynamic) 0.42mW(static)

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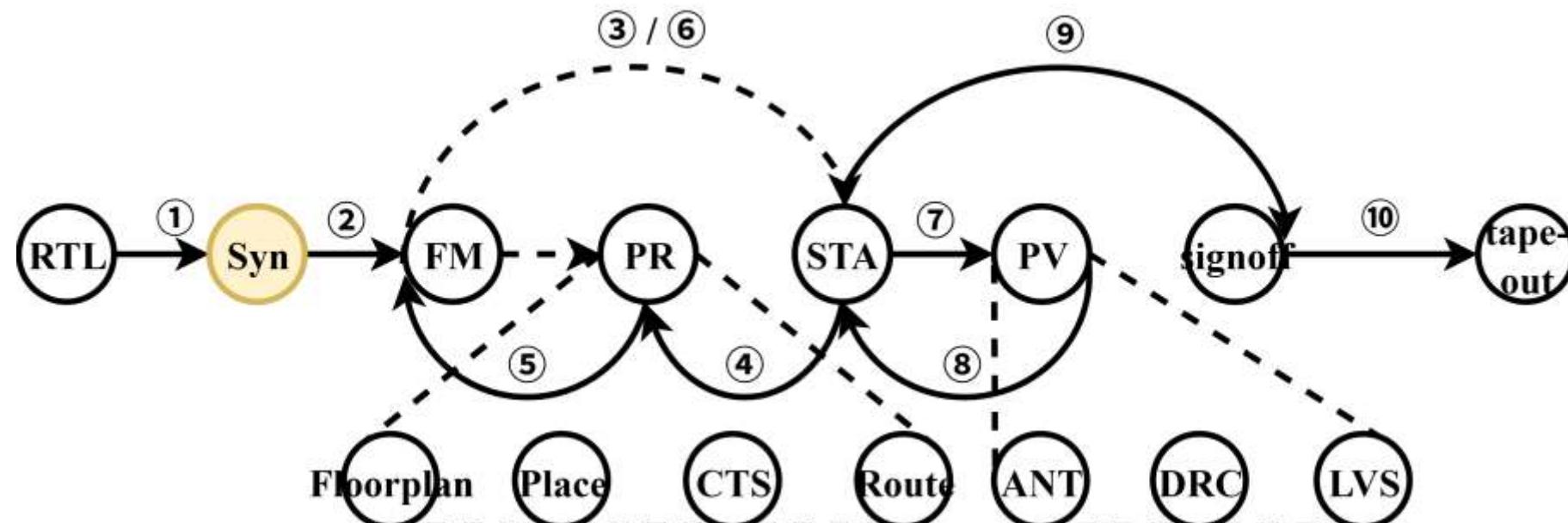
4. Place & Route

5. Physical verification

2. Synthesis

■ Synthesis (Syn)

- Synthesis involves mapping the front-end RTL code to a specific process library, adding constraint information, and logically optimizing the RTL code to generate a gate-level netlist. It is the process from **RTL** to **Gate-Level Netlist**

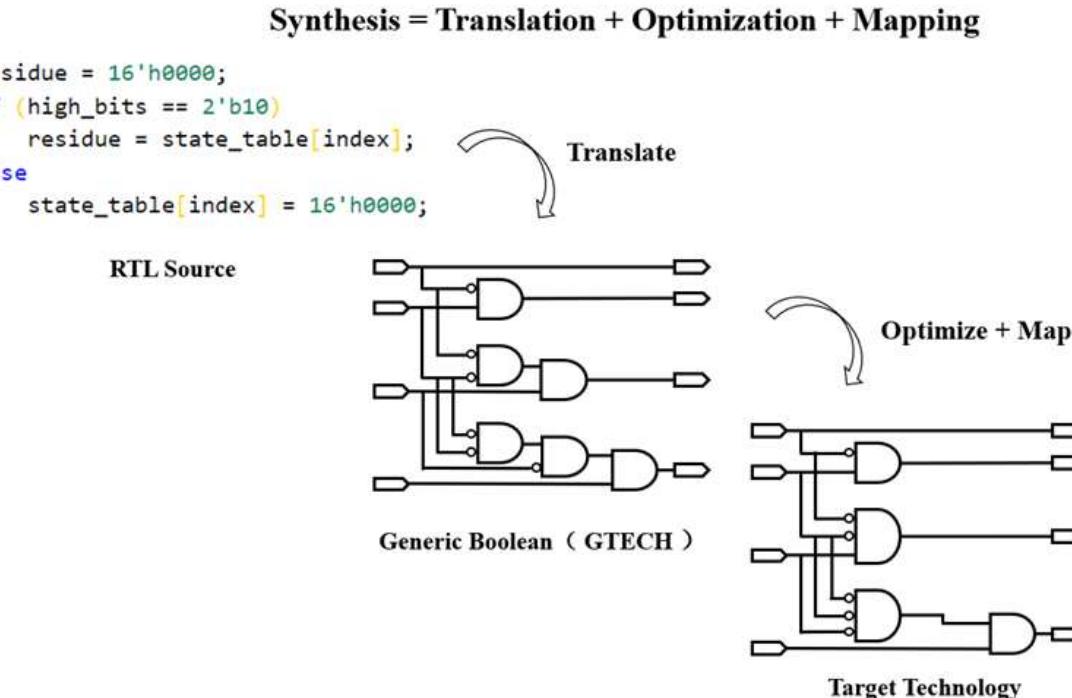
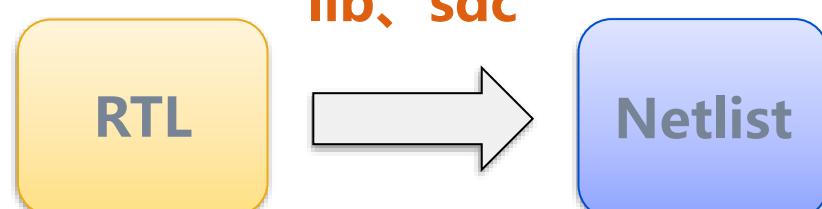


2. Synthesis

■ Synthesis : RTL to Gate-level Netlist generation

■ Input file:

- RTL Code (Verilog、VHDL)
- Library files (.lib/.db)
- Constraint files (.sdc)



lib、sdc

RTL

Netlist

Translation

- RTL translate to GTECH

Optimization

- Structural optimization
- Logic optimization

Mapping

- Optimized after mapping

2. Synthesis

■ Comparison of the RTL and Netlist files

```
1 module asic_top(
2     input clock,
3     input reset,
4     input in,
5     output out
6 );
7
8 reg reg_in;
9 reg reg_out;
10
11 always @(posedge clock or posedge reset)
12 begin
13     if (reset)begin
14         reg_in <= 1'b0;
15         reg_out <= 1'b0;
16     end
17     else begin
18         reg_in <= 1'b1;
19         reg_out <= reg_in ? in : 1'b0;
20     end
21 end
22
23 assign out = reg_out;
24
25 endmodule
```

RTL

VS

```
1 module asic_top (
2     clock,
3     in,
4     out,
5     reset
6 );
7
8 input clock ;
9 input in ;
10 output out ;
11 input reset ;
12
13 wire _0_ ;
14 wire _1_ ;
15 wire _2_ ;
16 wire clock ;
17 wire in ;
18 wire out ;
19 wire out_reg_p_D ;
20 wire reg_in ;
21 wire reset ;
22
23 AND2X16H7L _3_ ( .A(reg_in ), .B(in ), .Y(out_reg_p_D ) );
24 INVX0P5H7L _4_ ( .A(reset ), .Y(_0_ ) );
25 INVX0P5H7L _5_ ( .A(reset ), .Y(_1_ ) );
26 TIEHIH7H _6_ ( .Y(_2_ ) );
27 DFFRQX2H7L out_reg_p ( .CK(clock ), .D(out_reg_p_D ), .Q(out ), .RN(_0_ ) );
28 DFFRQX2H7L reg_in_reg_p ( .CK(clock ), .D(_2_ ), .Q(reg_in ), .RN(_1_ ) );
29
30 endmodule
```

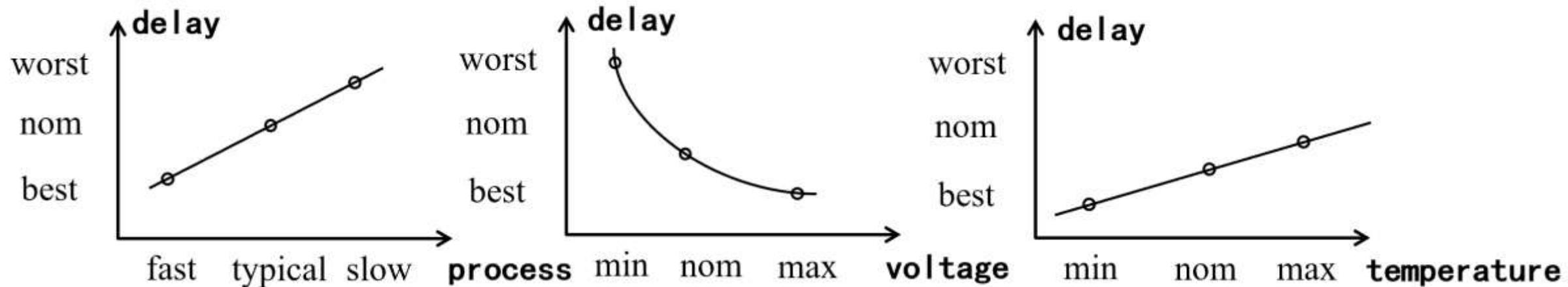
standard cell

netlist

2. Synthesis

■ PVT (Process, Voltage, Temperature)

- The speed of the process Corner, voltage level and temperature level will all affect the timing analysis results



- BC: ff_0p88v_m40c:
 - fast process
 - high power voltage
 - low temperature
- Typical: typical_0p8v_25c:
 - typical process
 - normal power voltage
 - normal temperature
- WC: ss_0p72v_125c:
 - slow process
 - low power voltage
 - high temperature

2. Synthesis

■ Synthesis report

- ≡ asic_top.area.rpt
- ≡ asic_top.check_design.pre.rpt
- ≡ asic_top.check_design.rpt
- ≡ asic_top.check_timing.rpt
- ≡ asic_top.clock_gating.rpt
- ≡ asic_top.clock.rpt
- ≡ asic_top.constraint.rpt
- ≡ asic_top.dont_touch.rpt
- ≡ asic_top.drc.rpt
- ≡ asic_top.power.rpt
- ≡ asic_top.qor.rpt
- ≡ asic_top.registers.rpt
- ≡ **asic_top.statistics.rpt**
- ≡ asic_top.timing.rpt



```
1 #-----  
2 # Area Area (μm2)  
3 #-----  
4 total std mem ipio sub_harden  
5 4219061.4 2221580.0 0.0 1997481.4 0.0  
6  
7 #-----  
8 # Cell Count Design scale  
9 #-----  
10 total std mem ipio sub_harden  
11 182428 182320 0 108 0  
12  
13 #-----  
14 # Vt/C1 ratio(area) Device type  
15 #-----  
16 SVT40 LVT40  
17 97.59 2.41  
18  
19 #-----  
20 # Timing Timing  
21 #-----  
22 group org_freq over_freq wns tns num  
23 CLK_u0_chiplink_rx_clk_pad_PAD 25.0 38.5 15.714 0.000 0  
24 CLK_u0_clk_XC 25.0 38.5 2.283 0.000 0  
25 CLK_u0_pll_CLK_OUT 100.0 153.8 0.000 0.000 0  
26 CLK_u1_clk_XC 100.0 153.8 0.006 0.000 0  
27 CLK_u1_pll_CLK_OUT 100.0 153.8 0.006 0.000 0
```

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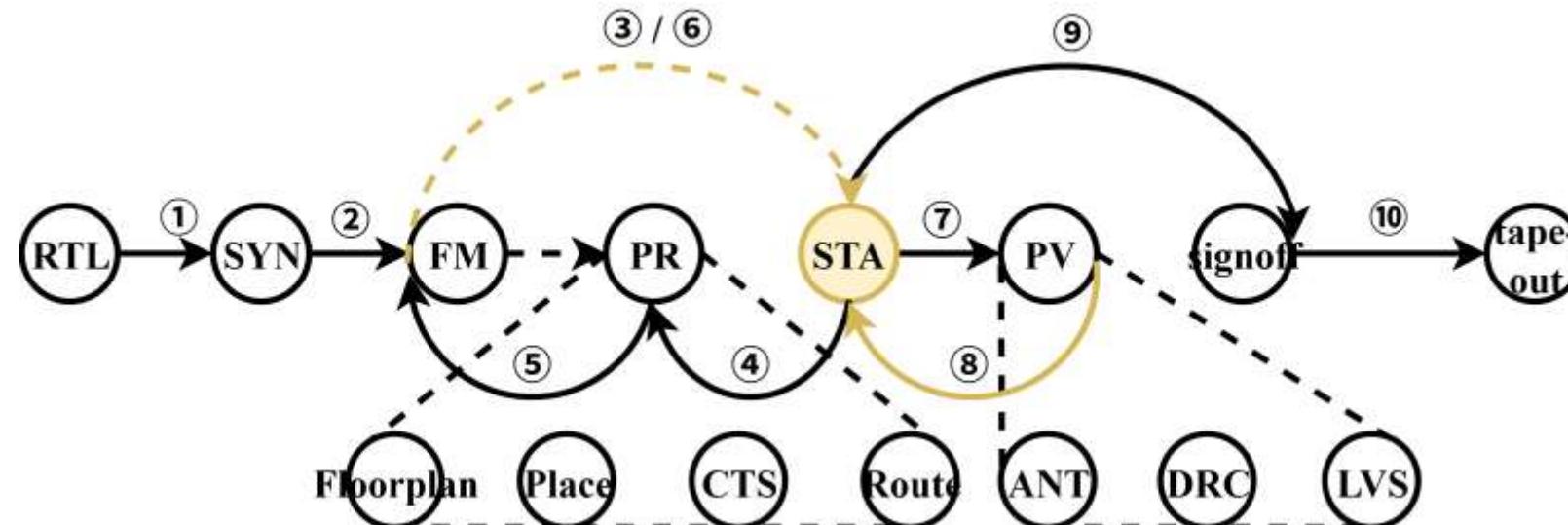
4. Place & Route

5. Physical verification

■ Static Timing Analysis (STA)

■ STA is the method for verifying the circuit timing by checking the timing information of all paths

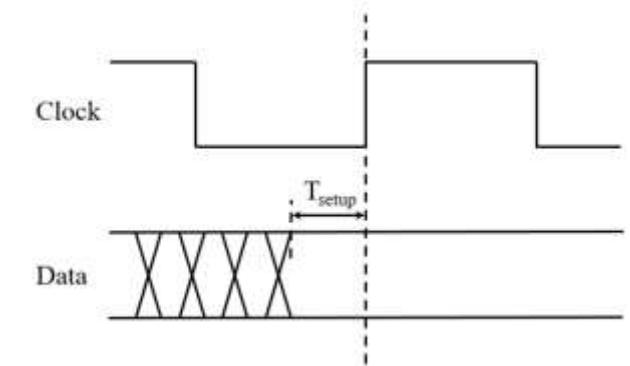
- Divide the design into several paths
- Calculate the delay of each path respectively
- Check whether the delay of each path meets the design constraints



3. Timing Analysis

■ Setup Time (T_{setup})

■ T_{setup} is the time when the data remains stable before the rising edge of the clock arrives



(1) The time when the data reaches the D end of UFF1 (arrival time):

$$T_a = T_{\text{launch}} + T_{\text{clk-q}} + T_{\text{logic}}$$

(2) Meet the maximum time allowed by setup (required time):

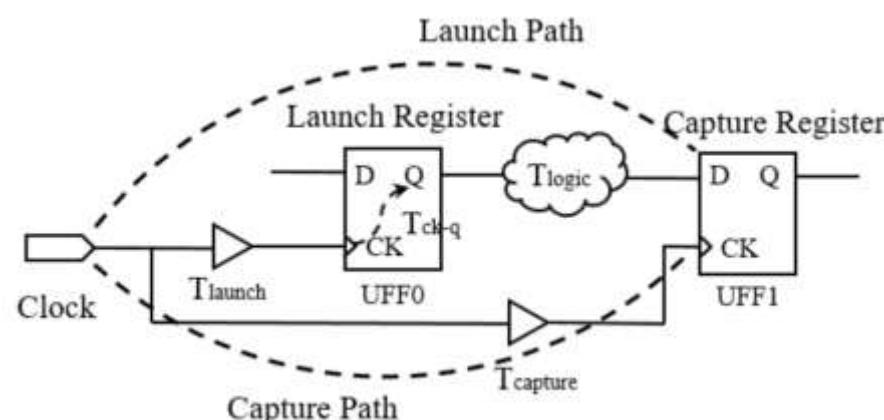
$$T_r = T_{\text{capture}} + T_{\text{clk}} - T_{\text{setup}}$$

(3) According to the setup time requirements, $T_r - T_a = T_{\text{margin}} \geq 0$

$$T_{\text{capture}} + T_{\text{clk}} - T_{\text{setup}} - T_{\text{launch}} - T_{\text{clk-q}} - T_{\text{logic}} \geq 0$$

(4) Let $T_{\text{capture}} - T_{\text{launch}} = T_{\text{skew}}$, and we get:

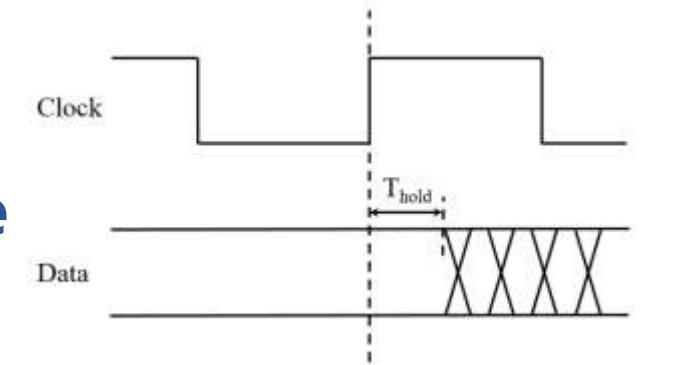
$$T_{\text{skew}} + T_{\text{clk}} \geq T_{\text{setup}} + T_{\text{clk-q}} + T_{\text{logic}}$$



3. Timing Analysis

■ Hold Time (T_{hold})

■ T_{hold} is the time when the data remains stable after the rising edge of the clock arrives



(1) The time when the data reaches the D end of UFF1 (arrival time) :

$$T_a = T_{\text{launch}} + T_{\text{ck-q}} + T_{\text{logic}}$$

2) Meet the maximum time allowed by hold (required time):

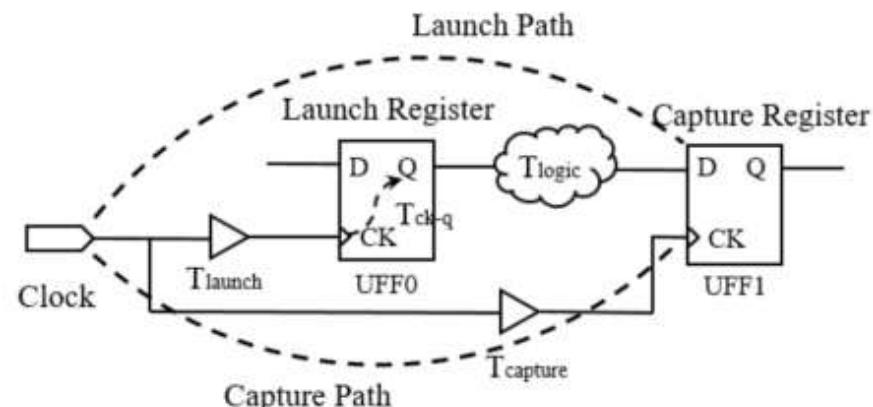
$$T_r = T_{\text{capture}} + T_{\text{hold}}$$

3) According to the hold time requirements, $T_a - T_r = T_{\text{margin}} \geq 0$

$$T_{\text{launch}} + T_{\text{ck-q}} + T_{\text{logic}} - T_{\text{capture}} - T_{\text{hold}} \geq 0$$

(4) Let $T_{\text{capture}} - T_{\text{launch}} = T_{\text{skew}}$, and we get:

$$T_{\text{skew}} + T_{\text{hold}} \leq T_{\text{ck-q}} + T_{\text{logic}}$$



■ Timing violation repair

- Method for fixing T_{setup} timing violations:

$$T_{\text{skew}} + T_{\text{clk}} \geq T_{\text{setup}} + T_{\text{ck-q}} + T_{\text{logic}}$$

- (1) Increase T_{clk} : Reduce frequency
- (2) Reduce T_{logic} : Optimize combinatorial logic, divide the pipeline, and reduce the load on the critical path
- (3) Reduce $T_{\text{ck-q}}$: Switch to faster logic units, such as HVT->LVT

- Method for fixing T_{hold} timing violations:

$$T_{\text{skew}} + T_{\text{hold}} \leq T_{\text{ck-q}} + T_{\text{logic}}$$

- (1) Increase T_{logic} : Increase the delay of the combined path and insert the buffer
- (2) Reduce T_{skew} : Even adopt a negative skew.

3.Timing Analysis (T_{setup})

Point	Incr	Path
clock (port)	0.000	0.000r
clock (clock net)		
ysyx_2025_my_ifu.curr_state_1_reg_p:CK (DFFQX1H7L)	0.000	0.000r
clock core_clock (rise edge)	0	0
clock network delay (ideal)	0.000	0.000
ysyx_2025_my_ifu.curr_state_1_reg_p:CK (DFFQX1H7L)	0.000	0.000r
ysyx_2025_my_ifu.curr_state_1_reg_p:Q (DFFQX1H7L)	0.089	0.089r
ysyx_2025_my_ifu.curr_state_1_(net)		
ysyx_2025_my_ifu.curr_state_1_BUFX8H7L_A:A (BUFX8H7L)	0.000	0.089r
ysyx_2025_my_ifu.curr_state_1_BUFX8H7L_A:Y (BUFX8H7L)	0.054	0.144r
mepc_7_INVX0P5H7L_A_Y_MUX2X0P5H7L_A_B_AOI21X0P5H7L_Y_A0_NOR2BX1P4H7L_Z_AN (net)		
.....		
ysyx_2025_gpr.rf[8]_18_reg_p_D_NOR2BX8H7L_Z:AN (NOR2BX8H7L)	0.000	1.738f
ysyx_2025_gpr.rf[8]_18_reg_p_D_NOR2BX8H7L_Z:Z (NOR2BX8H7L)	0.034	1.772f
ysyx_2025_gpr.rf[8]_18_reg_p_D (net)		
ysyx_2025_gpr.rf[8]_18_reg_p:D (DFFQX1H7L)	0.000	1.772f
clock (port)	0.000	0.000r
clock (clock net)		
ysyx_2025_gpr.rf[8]_0_reg_p_CK_ICGX0P5H7L_ECK:CK (ICGX0P5H7L)	0.000	0.000r
ysyx_2025_gpr.rf[8]_0_reg_p_CK_ICGX0P5H7L_ECK:ECK (ICGX0P5H7L)	0.000	0.000r
ysyx_2025_gpr.rf[8]_0_reg_p_CK (clock net)		
ysyx_2025_gpr.rf[8]_18_reg_p:CK (DFFQX1H7L)	0.000	0.000r
clock core_clock (rise edge)	10	10
clock network delay (ideal)	0.000	10.000
ysyx_2025_gpr.rf[8]_18_reg_p:CK (DFFQX1H7L)		10.000r
library setup time	-0.849	9.951
clock reconvergence pessimism	0.000	9.951
path cell delay		1.772(100.000%)
path net delay		0.000(0.000%)
data require time		9.951
data arrival time		1.772
slack (MET)		8.179

slack = $T_r - T_a = 9.951 - 1.772 = 8.179 > 0$, The timing meets the requirements.

3. Timing Analysis (T_{hold})

Point	Incr	Path
clock (port)	0.000	0.000r
clock (clock net)		
ysyx_2025_my_lsu.en_flash_0_reg_p:CK (DFFQX1H7L)	0.000	0.000r
clock core_clock (rise edge)	0	0
clock network delay (ideal)	0.000	0.000
ysyx_2025_my_lsu.en_flash_0_reg_p:CK (DFFQX1H7L)	0.000	0.000r
ysyx_2025_my_lsu.en_flash_0_reg_p:Q (DFFQX1H7L)	0.064	0.064f
ysyx_2025_my_lsu.en_flash_0_ (net)		
ysyx_2025_my_lsu.en_flash_1_reg_p:D (DFFQX1H7L)	0.000	0.064f
clock (port)	0.000	0.000r
clock (clock net)		
ysyx_2025_my_lsu.en_flash_1_reg_p:CK (DFFQX1H7L)	0.000	0.000r
clock core_clock (rise edge)	0	0
clock network delay (ideal)	0.000	0.000
ysyx_2025_my_lsu.en_flash_1_reg_p:CK (DFFQX1H7L)		0.000r
library hold time	-0.008	-0.008
clock reconvergence pessimism	-0.000	-0.008
path cell delay		0.064(100.000%)
path net delay		0.000(0.000%)
data require time		-0.008
data arrival time		0.064
slack (MET)		0.072

slack = $T_a - T_r = 0.064 - (-0.008) = 0.072 > 0$, The timing meets the requirements.

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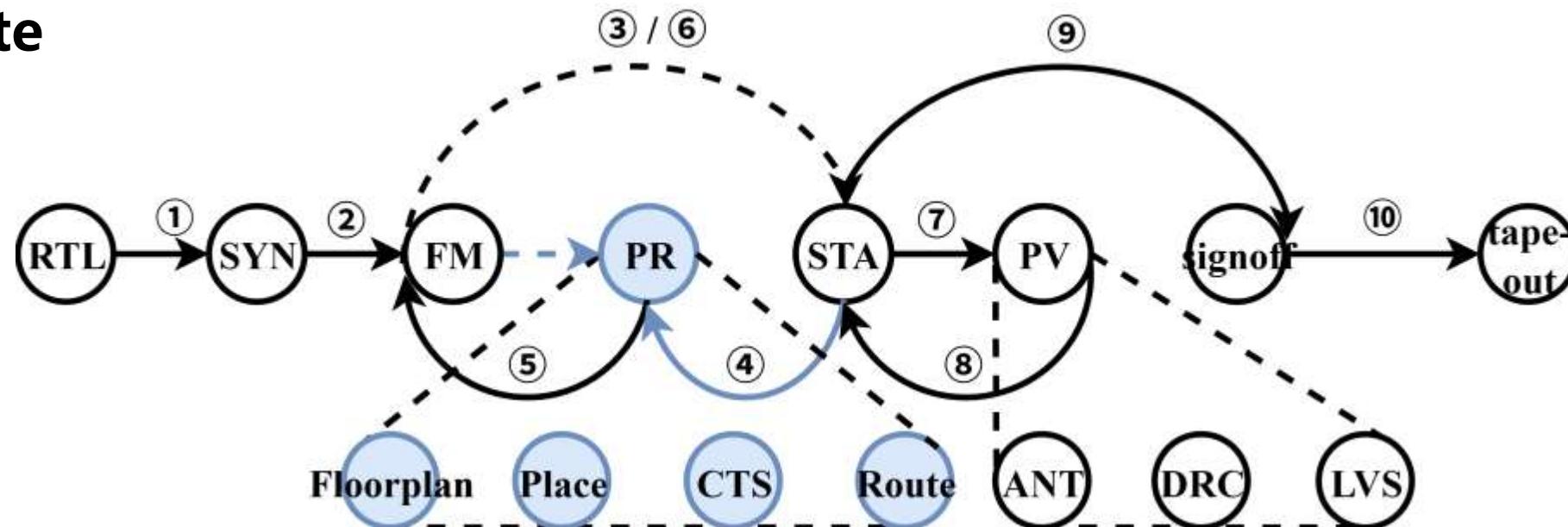
■ Place & Route(PR)

■ Floorplan

■ Place

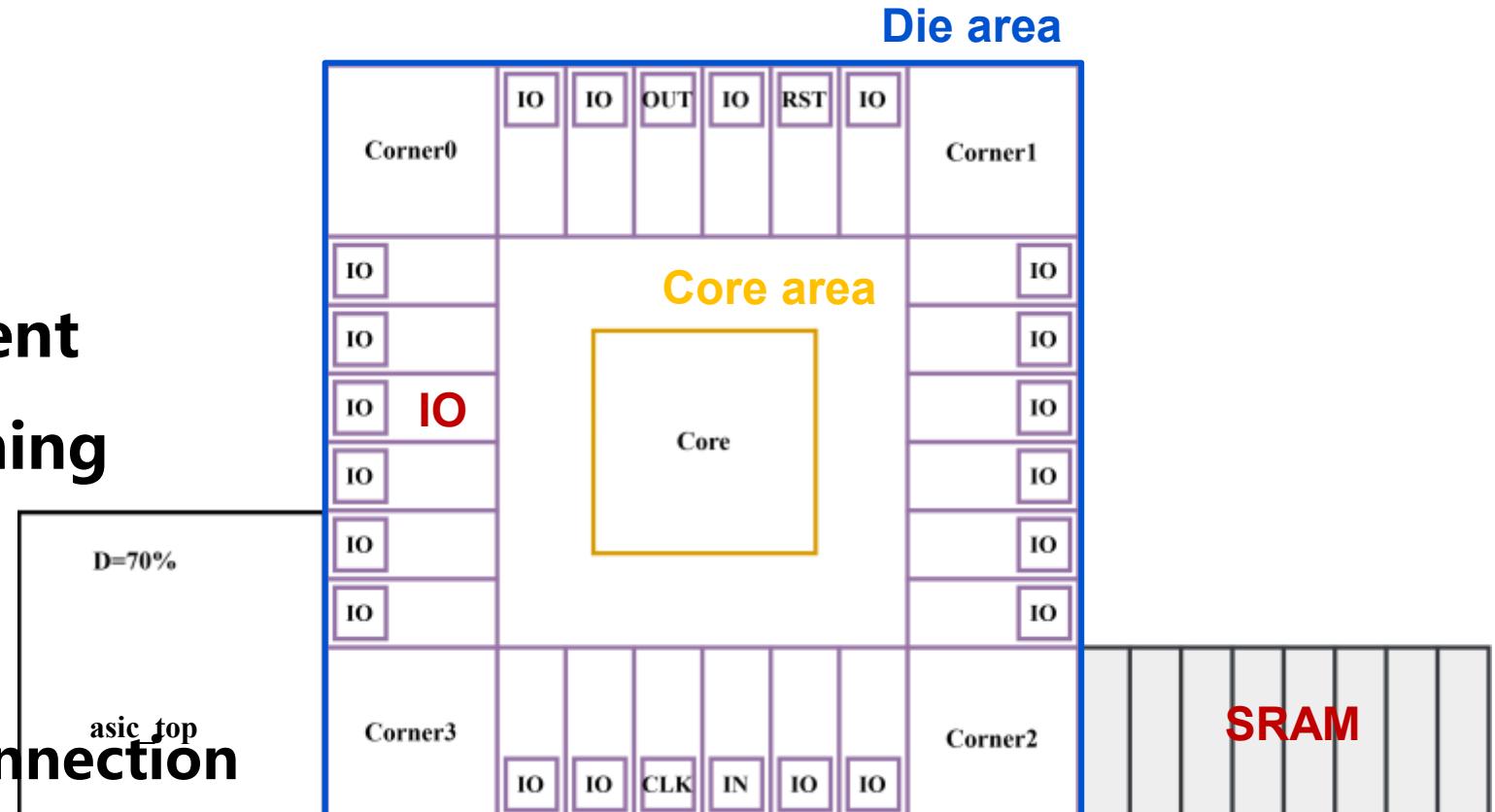
■ Clock Tree Synthesis(CTS)

■ Route



■ init & Floorplan

- Chip design input
- Chip I/O planning
- Macro unit placement
- Power supply planning
 - Power ring design
 - Power grid design
 - Power network connection



Chip utilization rate $D = (\text{Total area of standard units}) / (\text{Core area} - \text{SRAM})$

■ init & Floorplan

■ Chip design input

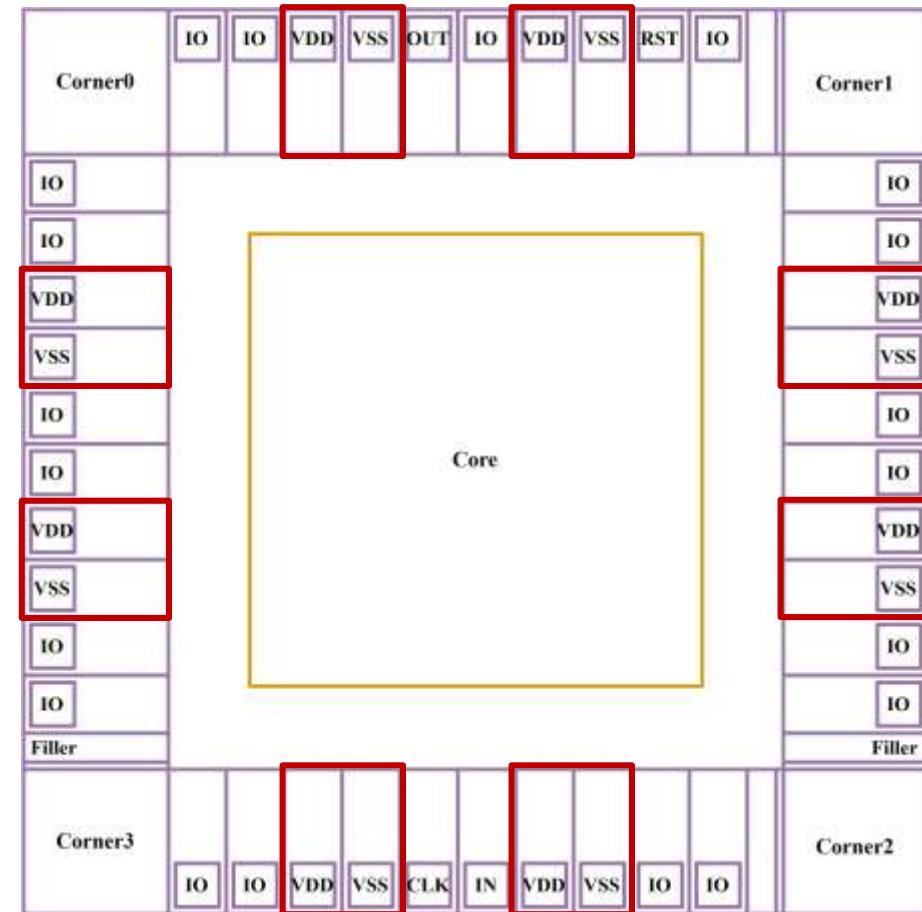
■ Chip I/O planning

■ Macro unit placement

■ Power supply planning

- Power ring design
- Power grid design
- Power network connection

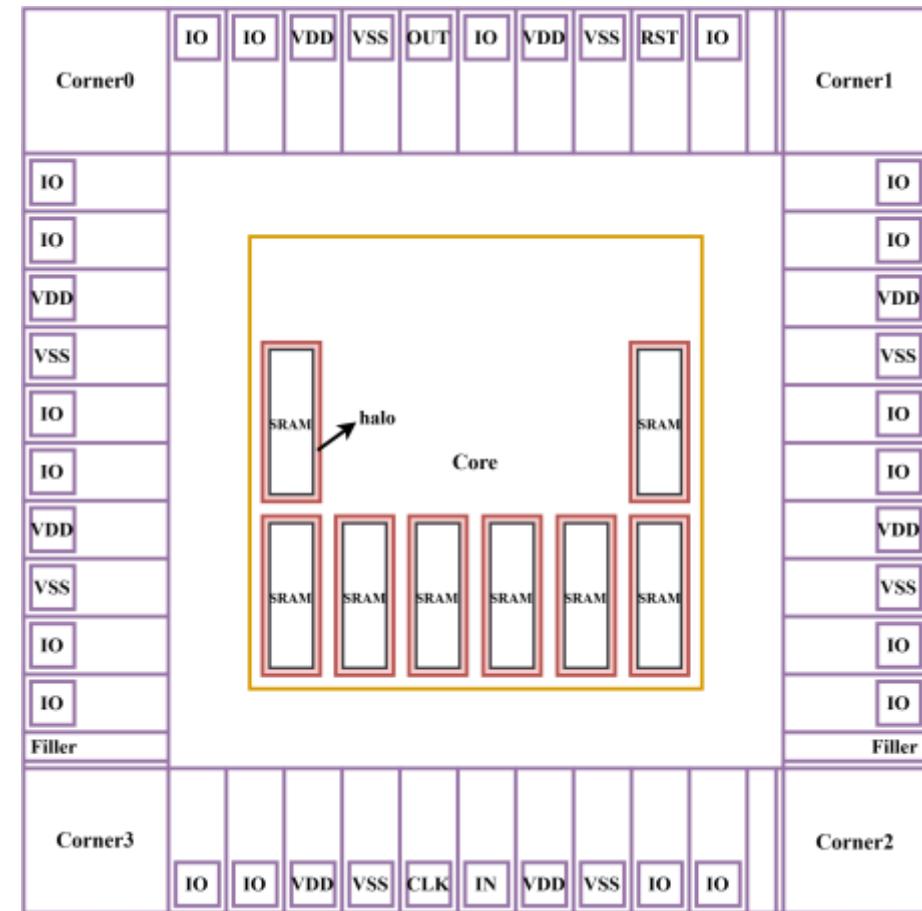
VDD/VSS



4. Place & Route

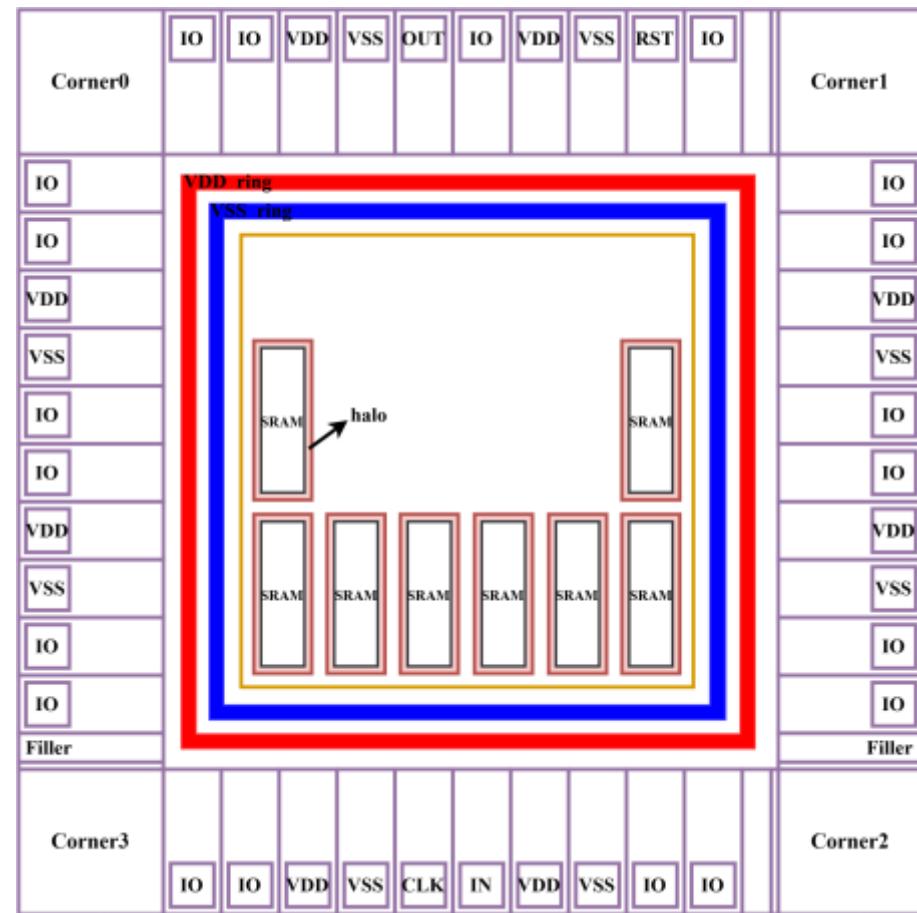
■ init & Floorplan

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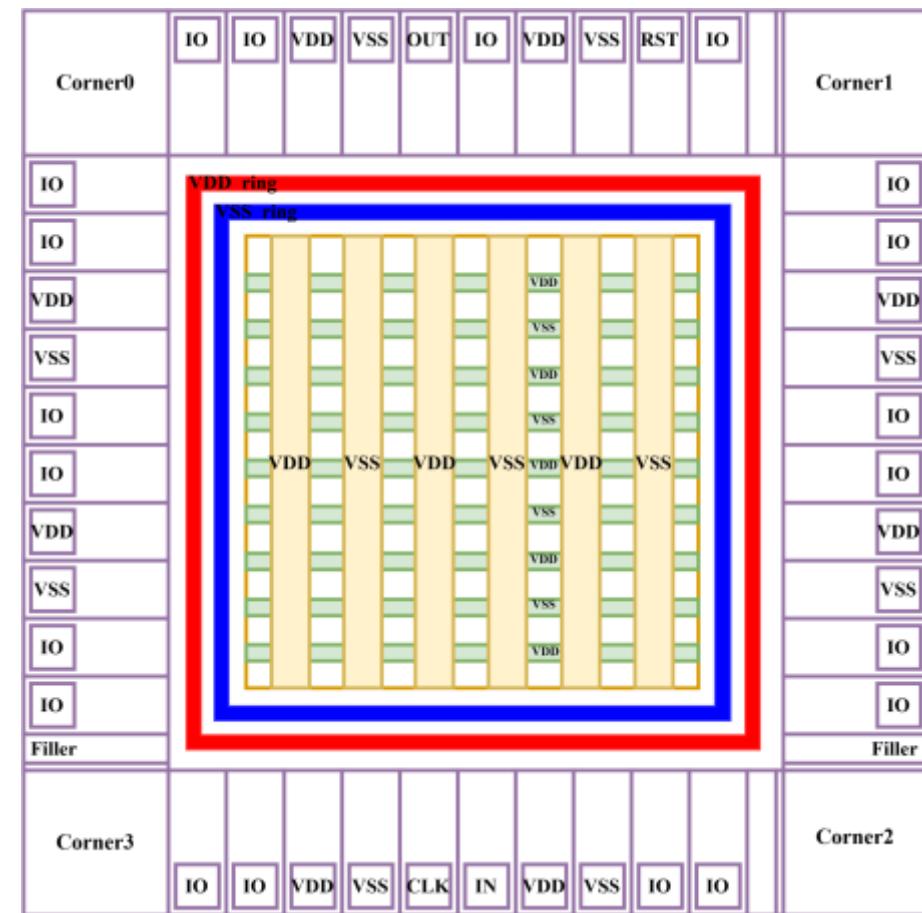
■ init & Floorplan

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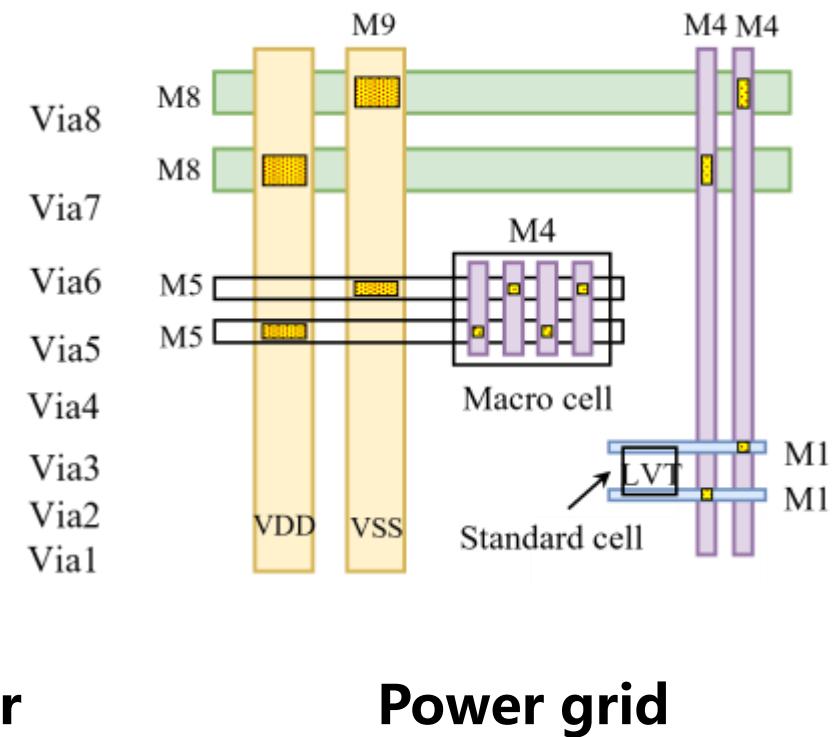
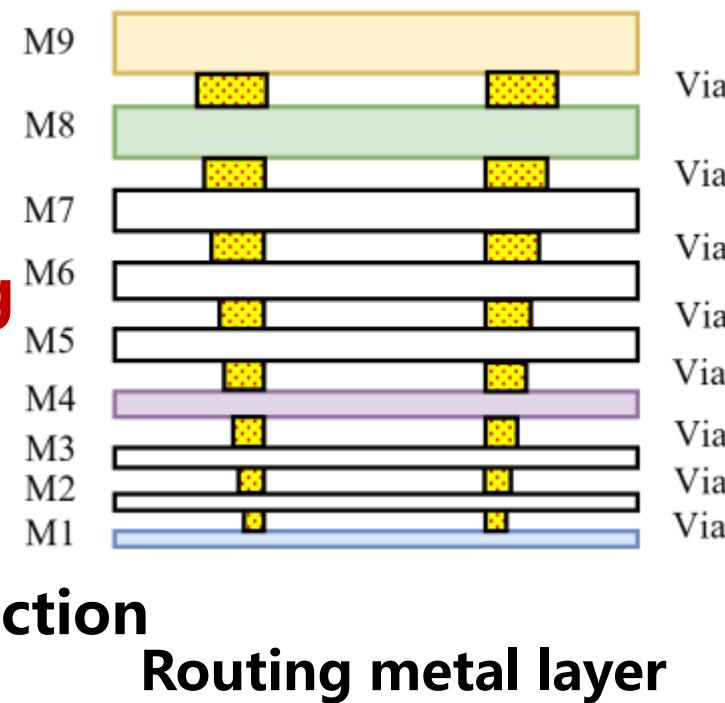


4. Place & Route

■ init & Floorplan

- Chip design input
- Chip I/O planning
- Macro unit placement
- Power supply planning

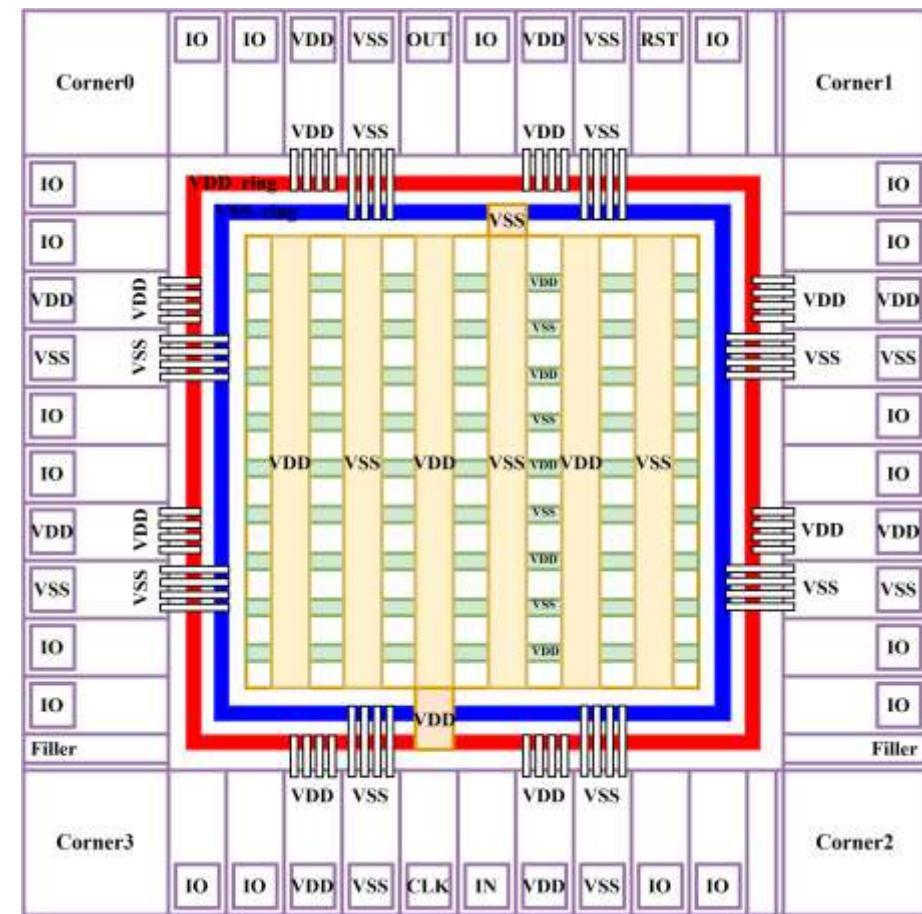
- Power ring design
- Power grid design
- Power network connection



4. Place & Route

■ init & Floorplan

- Chip design input
- Chip I/O planning
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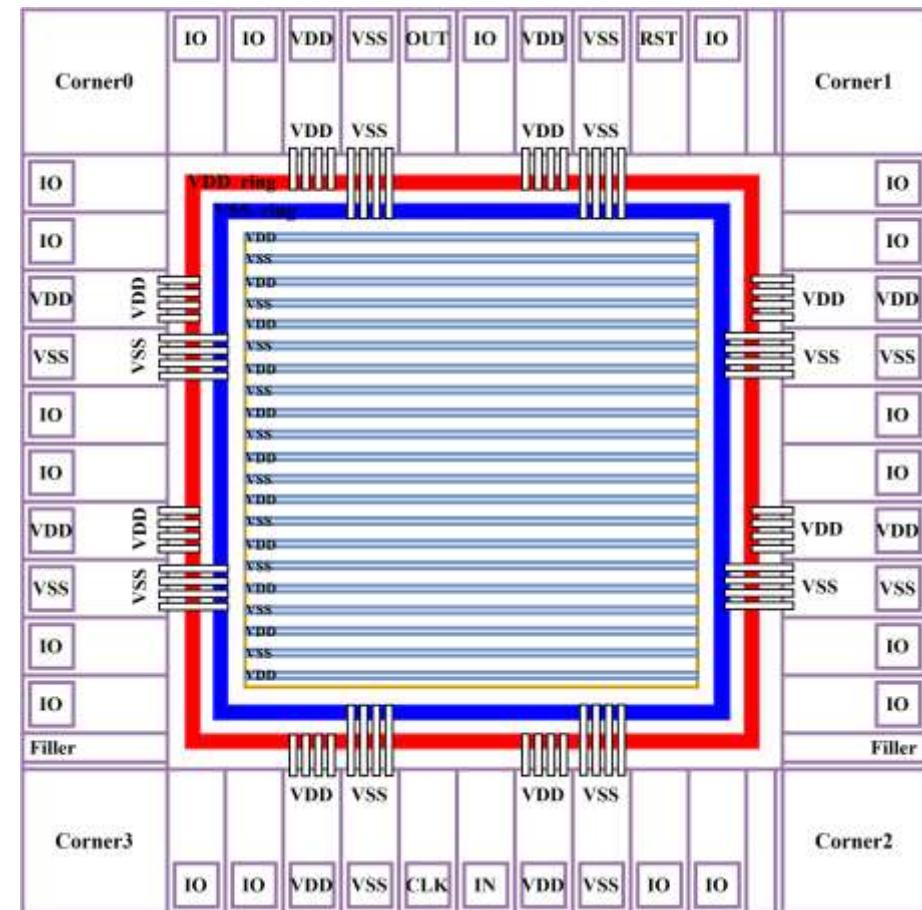
■ Place

■ The placement of standard units

- Global place
- Detail place

■ Optimization of standard units

- Whether it meets the timing sequence
- Whether it has sufficient resources



Before Place

4. Place & Route

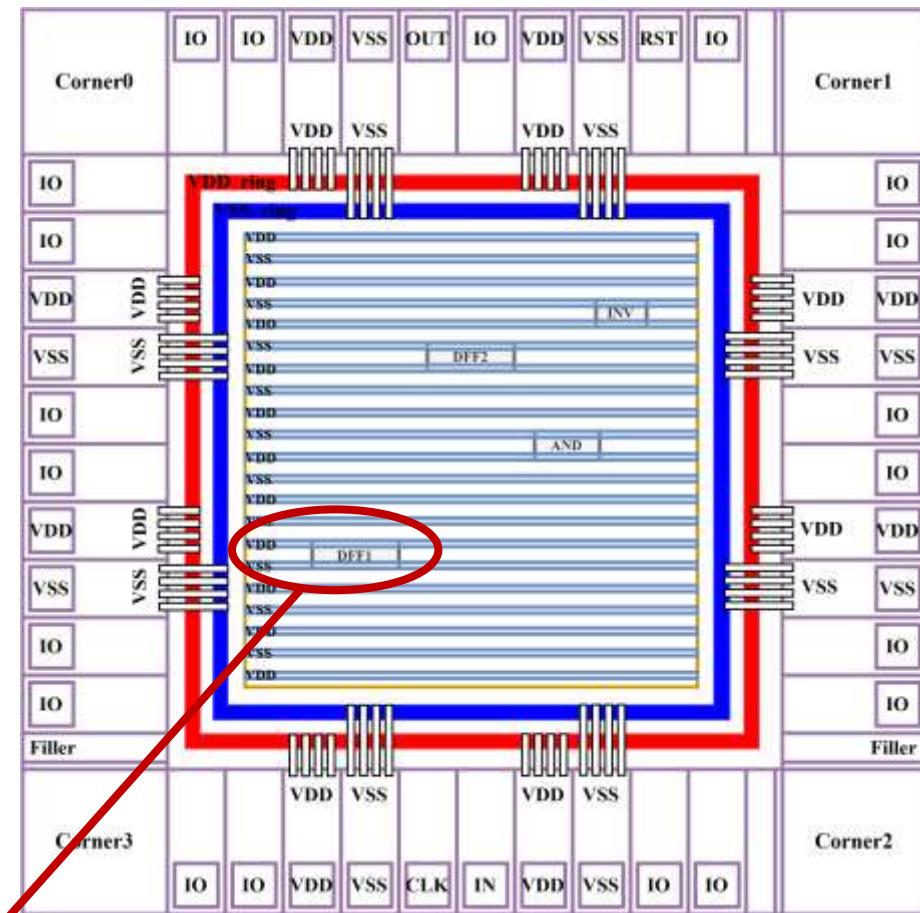
■ Place

■ The placement of standard units

- Global place
- Detail place

■ Optimization of standard units

- Whether it meets the timing sequence
- Whether it has sufficient resources



4. Place & Route

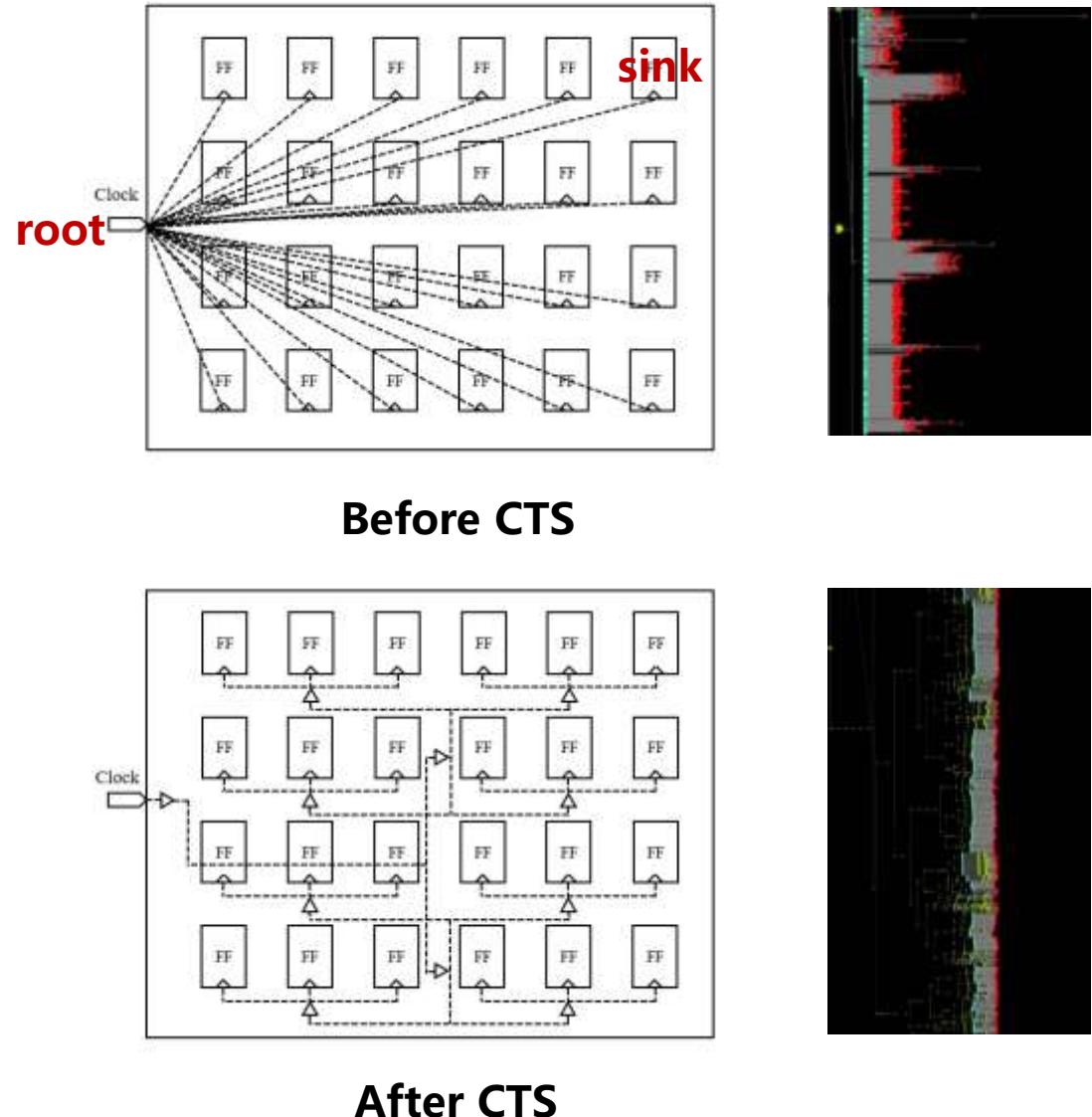
■ CTS

■ Growing clock tree

- The clock grows from the root point to each sink point
- The time skew of the clock reaching the clock terminals of each register should be as small as possible

■ Clock tree routing

■ Optimize the timing



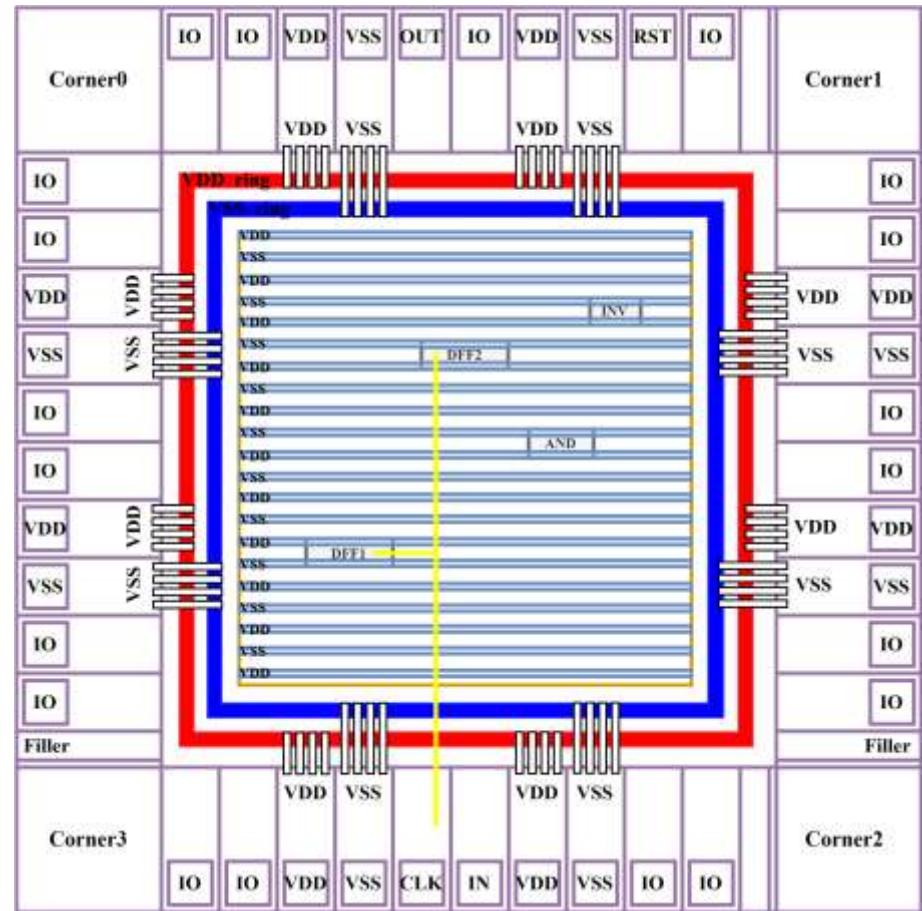
■ CTS

■ Growing clock tree

- The clock grows from the root point to each sink point
- The time skew of the clock reaching the clock terminals of each register should be as small as possible

■ Clock tree routing

■ Optimize the timing



■ Route

■ Global routing

- Plan the signal path and allocate wiring resources

■ Detail routing

- Implement the physical path to satisfy DRC

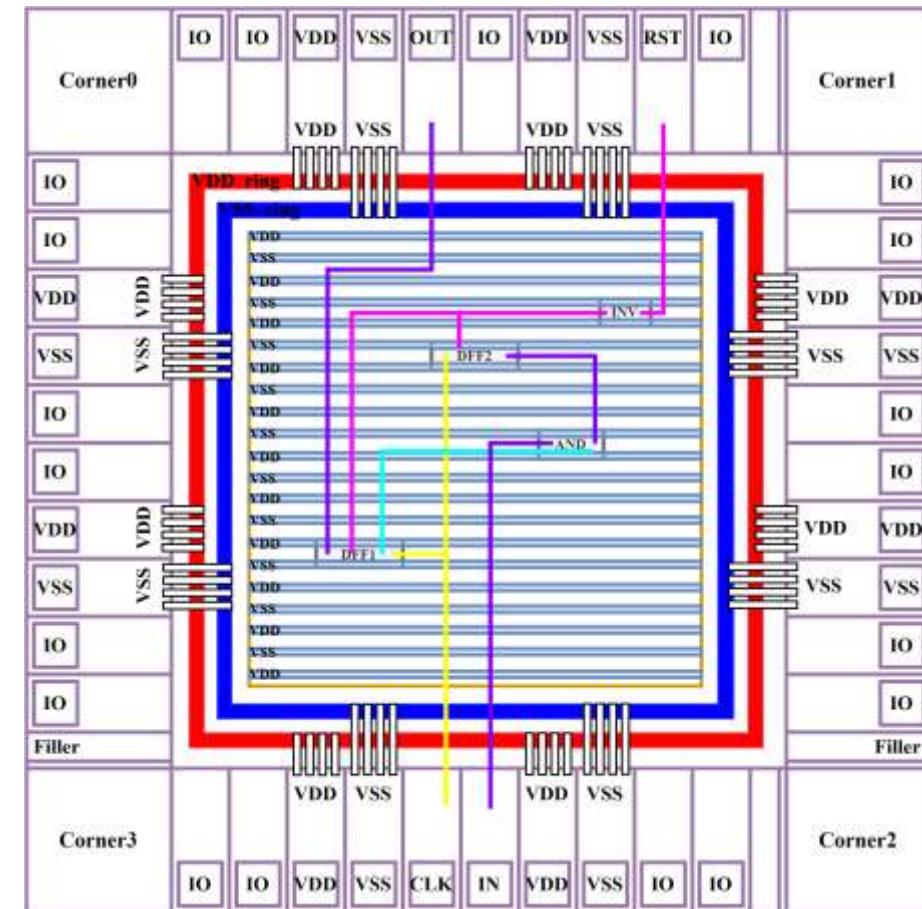
■ Search and repair

- Fix the violations after routing

■ Filler insert

■ Insert the standard Filler cell

- Connect the diffusion layer to form the power ground track



■ Route

■ Global routing

- Plan the signal path and allocate wiring resources

■ Detail routing

- Implement the physical path to satisfy DRC

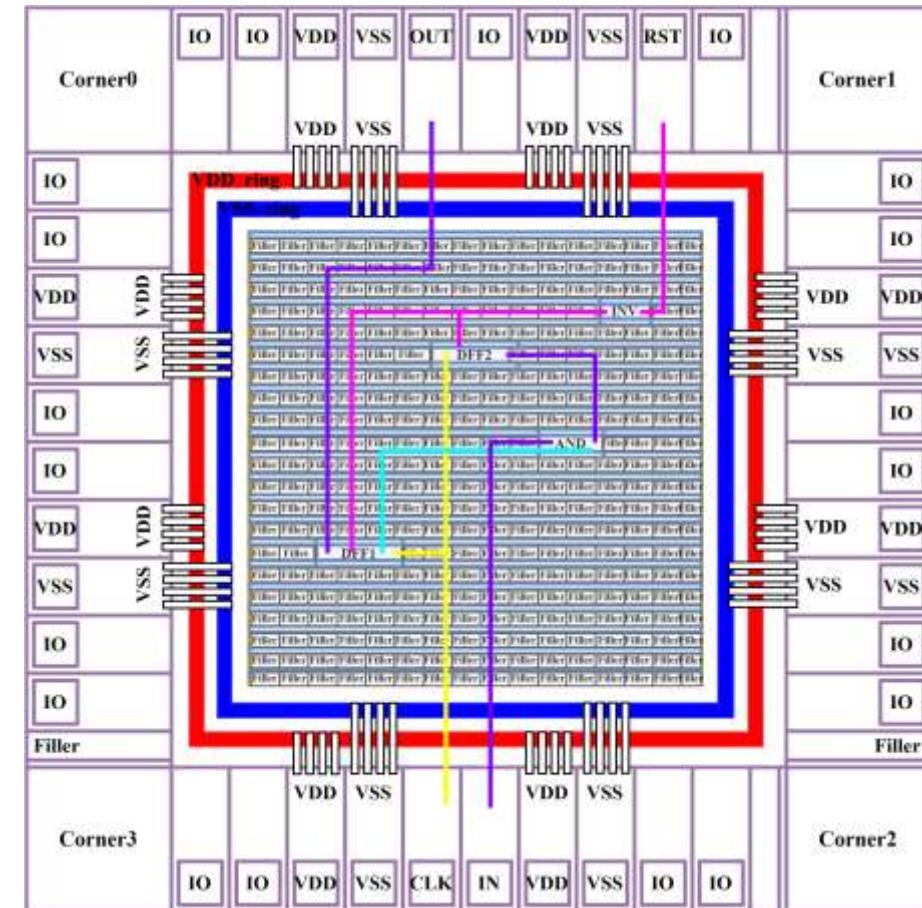
■ Search and repair

- Fix the violations after routing

■ Filler insert

■ Insert the standard Filler cell

- Connect the diffusion layer to form the power ground track



CONTENTS

1. Overview of the Back-end

2. Logical synthesis

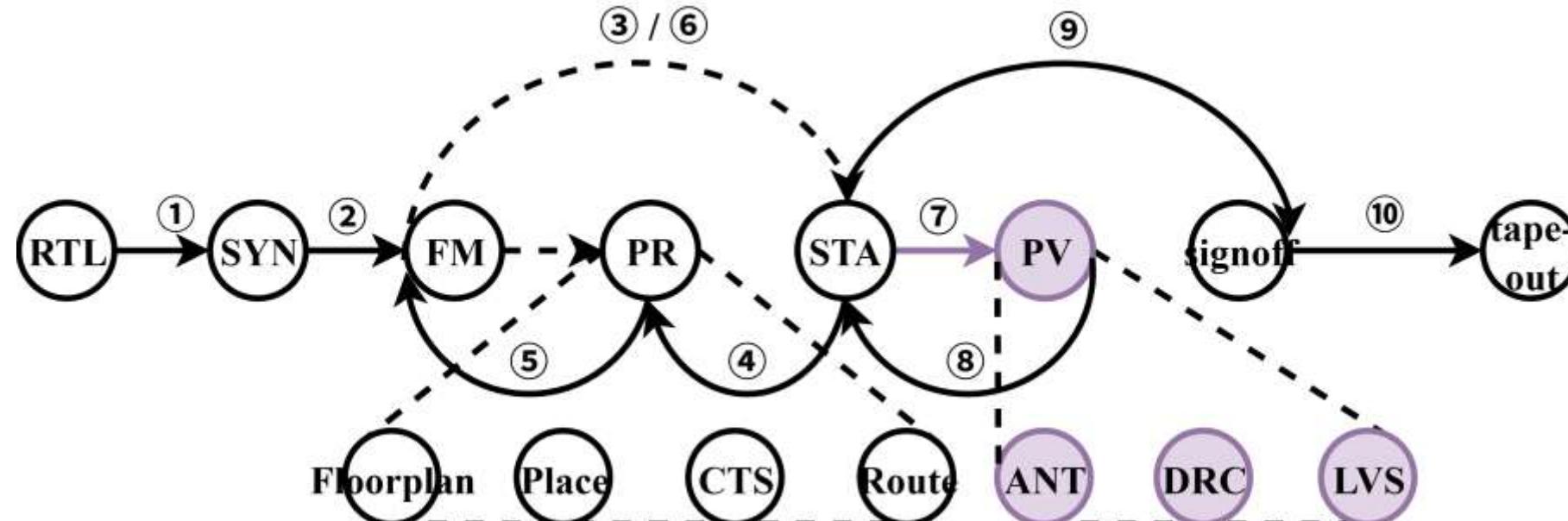
3. Timing analysis

4. Place & Route

5. Physical verification

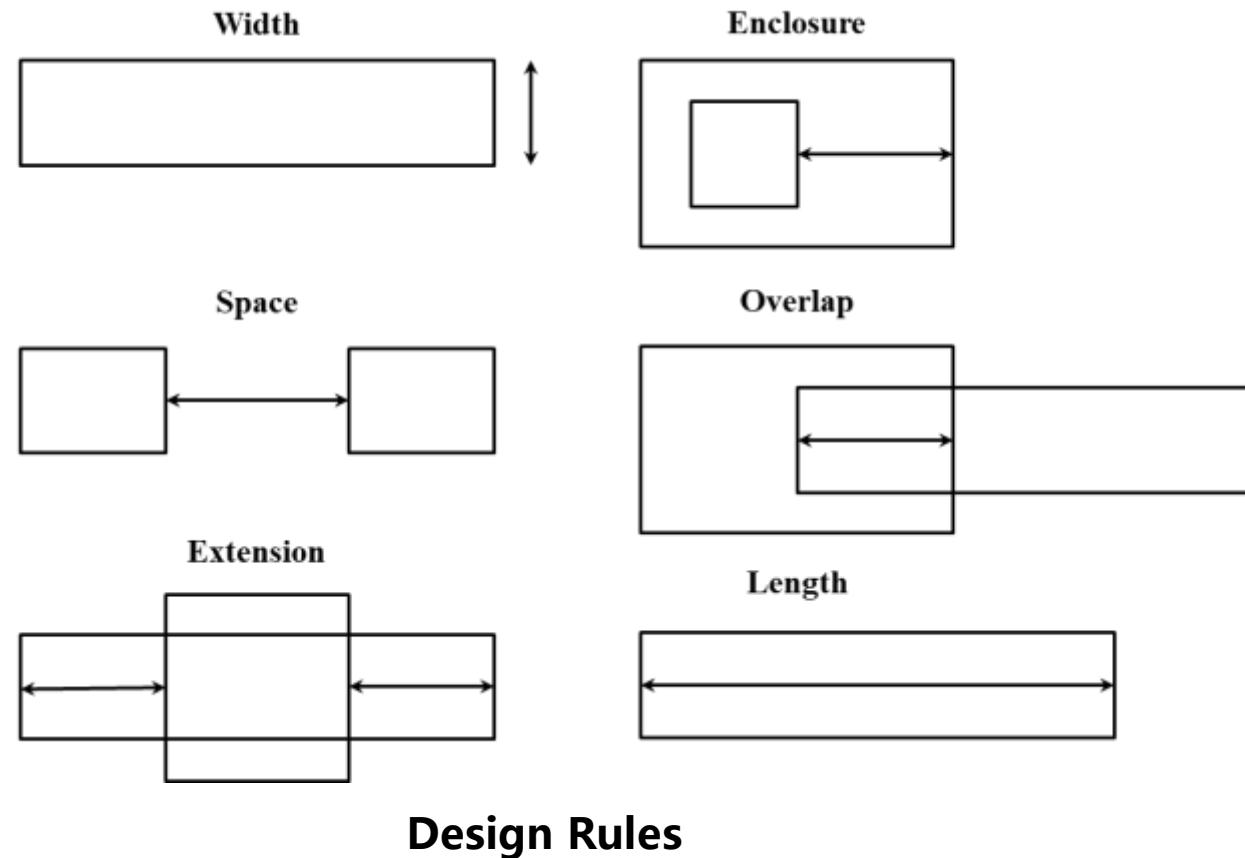
■ Physical Verification (PV)

- Electrical Rule Check (ERC)
- Design Rule Check (DRC)
- Layout Versus Schematic (LVS)



■ Design Rule Check (DRC)

- Ensure that the design of the chip layout complies with the design rules provided by the wafer fab (whether it can be manufactured)





Thanks!